

Due to variances in equipment, solder pastes and applications (board design, component density, etc.), Samtec does not specify a recommended reflow profile for our connectors. The processing parameters provided by the solder paste manufacturer should be employed and can usually be found on their website.

All of Samtec's surface mount components are lead free reflow compatible and compliant with the profile parameters detailed in IPC/JEDEC J-STD-020 which requires that components be capable of withstanding a peak temperature of 260°C as well as 30 seconds above 255°C. In addition, all of Samtec's surface mount components will withstand three reflow oven passes(*).

* Due to their weight and/or offset center of gravity some surface mount components cannot be processed while inverted without additional, mechanical support from locking clips, epoxy, etc.

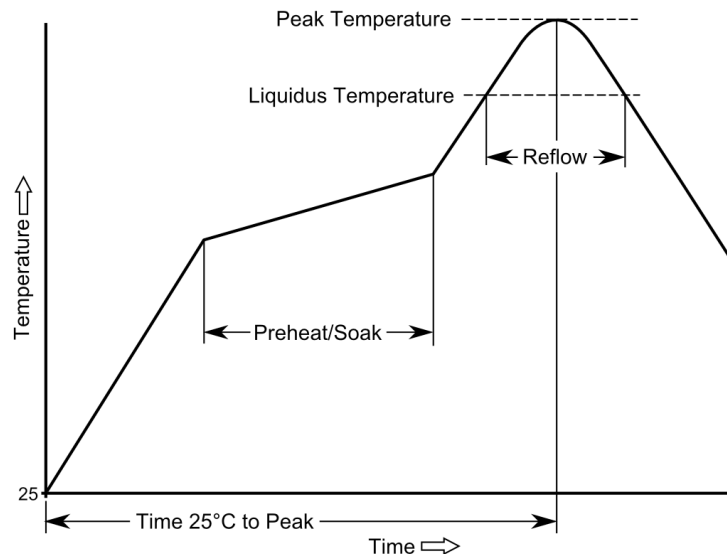
Samtec Recommended Temperature Profile Ranges (SMT)

Sn-Pb Eutectic Assembly

Preheat/Soak (100°C-150°C)	Max Ramp Up Rate	Reflow Time (Time above 183°C)	Peak Temperature	Time within 5°C of 235°C	Max Ramp Down Rate	Time 25°C to Peak Temperature
60-120 sec.	3°C/s max.	40-150 sec.	235°C	20 sec. max.	6°C/s max.	6 min. max.

Pb-Free Assembly

Preheat/Soak (150°C-200°C)	Max Ramp Up Rate	Reflow Time (Time above 217°C)	Peak Temperature	Time within 5°C of 260°C	Max Ramp Down Rate	Time 25°C to Peak Temperature
60-120 sec.	3°C/s max.	40-150 sec.	260°C	30 sec. max.	6°C/s max.	8 min. max.



For further discussion, please contact Samtec's Interconnect Processing Group (IPG) at ipg@samtec.com or 1-800-726-8329.

These guidelines should not be considered design requirements for all applications. Samtec recommends testing interconnects on your boards in your process to guarantee optimum results.